TDA9881

Alignment-free vision and FM sound IF PLL demodulator for negative modulated TV standards

Rev. 01 — 16 November 2004

Product data sheet



1. General description

The TDA9881 is an alignment-free multistandard (PAL and NTSC) vision and sound IF signal PLL demodulator for negative modulation, including Quasi Split Sound (QSS) or intercarrier FM processing.

2. Features

- 5 V supply voltage
- Gain controlled wideband Vision Intermediate Frequency (VIF) amplifier; AC-coupled
- Multistandard true synchronous demodulation for negative modulated standards with active carrier regeneration: very linear demodulation, good intermodulation figures, reduced harmonics and excellent pulse response
- Fully integrated VIF Voltage Controlled Oscillator (VCO), alignment-free, frequencies switchable via logic pin VIF0 and pin QSSO with resistor
- Digital acquisition help circuit, VIF frequencies of 38.0 MHz, 38.9 MHz, 45.75 MHz and 58.75 MHz
- 4 MHz reference frequency input signal from Phase-Locked Loop (PLL) tuning system or operating as crystal oscillator
- VIF Automatic Gain Control (AGC) detector for gain control; operating as peak sync detector
- VIF AGC monitor output at pin VAGC
- Precise fully digital Automatic Frequency Control (AFC) detector with 4-bit digital-to-analog converter
- TakeOver Point (TOP) adjustable with potentiometer
- Fully integrated sound carrier trap for 4.5 MHz, 5.5 MHz, 6.0 MHz and 6.5 MHz; controlled by FM PLL oscillator
- Sound IF (SIF) input for single reference Quasi Split Sound (QSS) mode; PLL controlled
- SIF AGC for gain controlled SIF amplifier; single reference QSS mixer able to operate in high performance single reference QSS mode or in intercarrier mode; switchable via SIF input pins
- Alignment-free selective FM PLL demodulator with high linearity and low noise.

3. Applications

TV, VTR, PC and Set-Top Box (STB) applications.



4. Quick reference data

Table 1: Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V_P	supply voltage		[1] [2]	4.5	5.0	5.5	V
l _P	supply current			52	63	70	mA
Video part							
$V_{i(VIF)(rms)}$	VIF input voltage sensitivity (RMS value)	-1 dB video at output		-	60	100	μV
G _{VIF(cr)}	VIF gain control range	see Figure 6		60	66	-	dB
f _{VIF}	vision carrier operating	see <u>Table 4</u>		-	38.0	-	MHz
	frequencies			-	38.9	-	MHz
				-	45.75	-	MHz
				-	58.75	-	MHz
Δf_{VIF}	VIF frequency window of digital acquisition help	related to f _{VIF} ; see Figure 9		-	±2.3	-	MHz
$V_{o(video)(p-p)}$	video signal output voltage (peak-to-peak value)	see Figure 4		1.7	2.0	2.3	V
G _{dif}	differential gain	"CCIR 330"; B/G standard	[3]	-	-	5	%
Φdif	differential phase	"CCIR 330"		-	2	4	deg
B _{video(-3dB)(trap)}	−3 dB video bandwidth including sound carrier trap	f _{trap} = 4.5 MHz	[4]	3.95	4.05	-	MHz
		$f_{trap} = 5.5 \text{ MHz}$	[4]	4.90	5.00	-	MHz
		$f_{trap} = 6.0 \text{ MHz}$	[4]	5.40	5.50	-	MHz
		f _{trap} = 6.5 MHz	<u>[4]</u>	5.50	5.95	-	MHz
α _{SC1}	trap attenuation at first sound	M/N standard		26	36	-	dB
	carrier	B/G standard		26	36	-	dB
S/N _{W(video)}	weighted signal-to-noise ratio of video signal	weighted in accordance with "CCIR 567"; see Figure 10	[5]	55	-	-	dB
PSRR _{CVBS}	power supply ripple rejection at pin CVBS	f _{ripple} = 70 Hz; see Figure 5	[6]	20	25	-	dB
AFC _{stps}	AFC control steepness	definition: $\Delta I_{AFC}/\Delta f_{VIF}$		0.85	1.05	1.25	μA/kHz
Audio part							
$V_{o(AF)(rms)}$	AF output voltage (RMS value)	27 kHz FM deviation; 50 μs de-emphasis		430	540	650	mV
THD	total harmonic distortion of audio signal	FM: 27 kHz FM deviation; 50 μs de-emphasis		-	0.15	0.50	%
B _{AF(-3dB)}	−3 dB AF bandwidth	without de-emphasis; dependent on FM PLL filter		80	100	-	kHz
S/N _{W(AF)}	weighted signal-to-noise ratio of audio signal	FM: 27 kHz FM deviation; 50 µs de-emphasis; vision carrier unmodulated		52	56	-	dB
α _{AM(sup)}	AM suppression of FM demodulator	50 μs de-emphasis; AM: f = 1 kHz and m = 54 %; referenced to 27 kHz FM deviation		40	46	-	dB
9397 750 13417					© Koninklijke Philips El	ectronics N.V. 20	04. All rights reserve

Table 1: Quick reference data ...continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
PSRR _{FMSO}	power supply ripple rejection on pin FMSO	FM: f _{ripple} = 70 Hz; see <u>Figure 5</u>	14	20	-	dB
V _{o(intc)(rms)}	IF intercarrier output level	QSS mode; SC ₁ ; SC ₂ off	90	140	210	mV
	(RMS value)	intercarrier mode; PC/SC ₁ = 20 dB; SC ₂ off	<u>[7]</u> -	75	-	mV
Reference from	equency					
f _{ref}	reference signal frequency		[8]	4	-	MHz
V _{ref(rms)}	reference signal voltage (RMS value)	operation as input terminal	80	-	400	mV

- [1] Values of video and sound parameters can be decreased at $V_P = 4.5 \text{ V}$.
- [2] The time constant (R \times C) at the supply must be > 1.2 μ s (e.g. 1 Ω and 2.2 μ F).
- [3] Condition: luminance range (5 steps) from 0 % to 100 %.
- [4] AC load: $C_L < 20$ pF and $R_L > 1$ k Ω . The sound carrier frequencies (depending on the TV standard) are attenuated by the integrated sound carrier traps (see Figure 12 to Figure 17; |H(s)| is the absolute value of the transfer function).
- [5] $S/N_{W(video)}$ is the ratio of the black-to-white amplitude to the black level noise voltage (RMS value measured on pin CVBS). B = 5 MHz (B/G, I and D/K standard). Noise analyzer setting: 200 kHz high-pass and SC-trap switched on.
- [6] Conditions: video signal, grey level and negative modulation.
- [7] The intercarrier output signal at pin QSSO can be calculated by the following formula taking into account the internal video signal with 1.1 V (p-p) as a reference:

$$V_{\text{o(intc)}} = 1.1 \text{ V (p-p)} \times \frac{1}{2\sqrt{2}} \times 10^{\frac{V_{i(SC)}}{V_{i(PC)}}(dB) + 6 \text{ dB} \pm 3 \text{ dB}}{20}$$
 (RMS)

where: $\frac{1}{2\sqrt{2}}$ is the correction term for RMS value, $\frac{V_{i(SC)}}{V_{i(PC)}}(dB)$ is the sound-to-picture carrier ratio at pins VIF1 and VIF2 in dB, 6 dB is

the correction term of internal circuitry and \pm 3 dB is the tolerance of video output and intercarrier output $V_{o(intc)(rms)}$.

[8] Pin REF is able to operate as a 1-pin crystal oscillator input as well as an external reference signal input, e.g. from the tuning system.

5. Ordering information

Table 2: Ordering information

Type number	Package						
	Name	Description	Version				
TDA9881TS	SSOP24	plastic shrink small outline package; 24 leads; body width 5.3 mm	SOT340-1				
TDA9881HN	HVQFN32	plastic thermal enhanced very thin quad flat package; no leads; 32 terminals; body $5\times5\times0.85~\text{mm}$	SOT617-3				

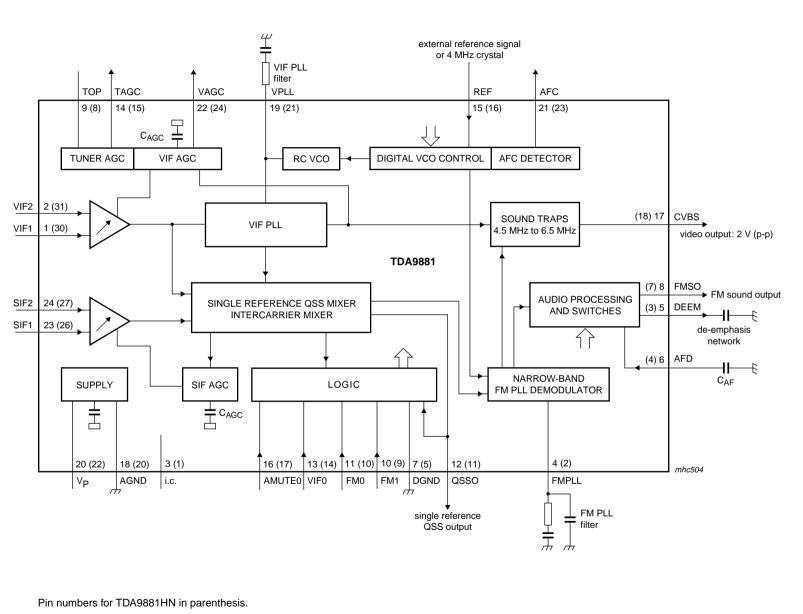
Product data sheet

3 of 42

DA9881

Block diagram

9



9397 750 13417

Product data sheet

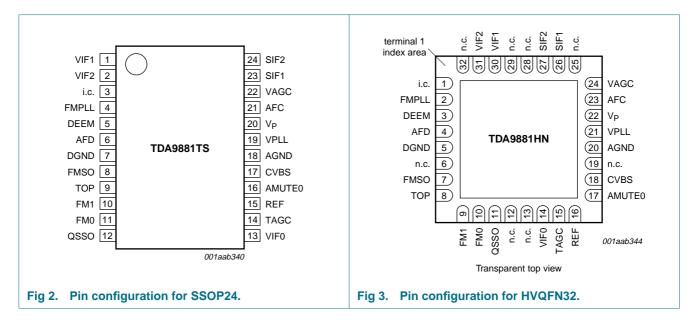
Rev. 01

16 November 2004

www.DataSheet4U.com

7. Pinning information

7.1 Pinning



www.DataSheet4U.com

7.2 Pin description

Table 3: Pin description

Symbol	Pin		Description
Symbol		TDA0004UN	Description
VIF1	TDA9881TS	TDA9881HN	VIE differential input 1
VIF1		30	VIF differential input 1
	2	31	VIF differential input 2
n.c.	-	32	not connected
i.c.	3	1	internally connected; leave open
FMPLL	4	2	FM PLL for loop filter
DEEM	5	3	de-emphasis output for capacitor
AFD	6	4	AF decoupling input for capacitor
DGND	7	5	digital ground
n.c.	-	6	not connected
FMSO	8	7	FM sound output
TOP	9	8	tuner AGC TakeOver Point (TOP) for resistor adjustment
FM1	10	9	FM IF select bit 1
FM0	11	10	FM IF select bit 0
QSSO	12	11	single reference QSS output and vision IF select bit 1 with resistor
n.c.	-	12	not connected
n.c.	-	13	not connected
VIF0	13	14	vision IF select bit 0
TAGC	14	15	tuner AGC output
REF	15	16	4 MHz crystal or reference signal input
AMUTE0	16	17	auto mute select bit 0
CVBS	17	18	composite video output
n.c.	-	19	not connected
AGND	18	20	analog ground
VPLL	19	21	VIF PLL for loop filter
V _P	20	22	supply voltage
AFC	21	23	AFC output
VAGC	22	24	vision AGC output
n.c.	-	25	not connected
SIF1	23	26	SIF differential input 1 and intercarrier mode select
SIF2	24	27	SIF differential input 2 and intercarrier mode select
n.c.	-	28	not connected
n.c.	-	29	not connected
			•

8. Functional description

A simplified block diagram of the device is illustrated in <u>Figure 1</u>. The device contains the following functional blocks:

- 1. VIF amplifier
- 2. Tuner AGC and VIF AGC
- 3. VIF AGC detector
- 4. Frequency Phase-Locked Loop (FPLL) detector
- 5. VCO and divider
- 6. AFC and digital acquisition help circuit
- 7. Video demodulator and amplifier
- 8. Sound carrier trap
- 9. SIF amplifier
- 10.SIF AGC detector
- 11. Single reference QSS mixer
- 12.FM demodulator and acquisition help circuit
- 13. Audio amplifier and mute time constant
- 14.Internal voltage stabilizer
- 15.Logic.

8.1 VIF amplifier

The VIF amplifier consists of three AC-coupled differential stages. Gain control is performed by emitter degeneration. The total gain control range is typical 66 dB. The differential input impedance is typical 2 k Ω in parallel with 3 pF.

8.2 Tuner AGC and VIF AGC

This block adapts the voltage, generated at the VIF AGC detector, to the internal signal processing at the VIF amplifier and performs the tuner AGC control current generation. The onset of the tuner AGC control current generation can be set by a potentiometer at pin TOP.

8.3 VIF AGC detector

Gain control is performed using sync level detection.

The sync level voltage is stored in an integrated capacitor by means of a fast peak detector. This voltage is compared with a reference voltage (nominal sync level) by a comparator which charges or discharges the integrated AGC capacitor to generate the VIF gain. The time constants for decreasing or increasing the gain are nearly equal and the total AGC reaction time is fast, to cope with 'aeroplane fluttering'.

8.4 FPLL detector

The VIF amplifier output signal is fed to a frequency detector and a phase detector via a limiting amplifier to remove the video AM.

During acquisition the frequency detector produces a current that is proportional to the frequency difference between the VIF and the VCO signal. After frequency lock-in the phase detector produces a current that is proportional to the phase difference between the VIF and the VCO signal. The currents from the frequency and phase detector are charged into the loop filter which controls the VIF VCO and locks it to the frequency and phase of the VIF carrier.

8.5 VCO and divider

The VCO of the VIF FPLL operates as an integrated low radiation relaxation oscillator at twice the picture carrier frequency. The control voltage, required to tune the VCO to actually double the picture carrier frequency, is generated at the loop filter by the frequency phase detector. The possible frequency range is 50 MHz to 140 MHz (typical value).

The oscillator frequency is divided-by-two to provide two differential square wave signals with exactly 90 degrees phase difference, independent of the frequency, for use in the FPLL detectors, the video demodulator and the single reference QSS or intercarrier mixer.

8.6 AFC and digital acquisition help circuit

Each relaxation oscillator of the VIF PLL and FM PLL demodulator has a wide frequency range. To prevent false locking of the PLLs, with respect to the catching range, the digital acquisition help circuit provides an individual control until the frequency of the VCO is within the preselected standard dependent lock-in window of the PLL.

The VIF carrier frequencies 38.0 MHz, 38.9 MHz (M/N, B/G, I and D/K standard) and 45.75 MHz, 58.75 MHz (NTSC standard) can be selected via pin VIF0 and pin QSSO with resistor; see Table 4.

The FM carrier frequencies can be selected via pin FM0 and pin FM1; see Table 5.

The in-window and out-window control at the FM PLL can additionally be used to mute the audio stage (if auto mute is selected via pin AMUTE0); see <u>Table 6</u>.

The principle working of the digital acquisition help circuit is as follows: The PLL VCO output is connected to a downcounter which has a predefined start value (standard dependent). The VCO frequency clocks the downcounter for a fixed gate time. Thereafter, the downcounter stop value is analyzed. In the event that the stop value is higher (lower) than the expected value range, the VCO frequency will be lower (higher) than the required lock-in window frequency range. A positive (negative) control current is injected into the PLL loop filter which causes the VCO frequency to be increased (decreased) and a new counting cycle starts.

The gate time as well as the control logic of the acquisition help circuit is dependent on the precision of the reference signal at pin REF. Operation as a crystal oscillator is possible as well as connecting this input via a serial capacitor to an external reference frequency e.g. the tuning system oscillator.

www.DataSheet4U.com

The AFC signal is derived from the corresponding downcounter stop value after a counting cycle. The last four bits are latched and the digital-to-analog converted value is given as current at pin AFC.

8.7 Video demodulator and amplifier

The video demodulator is realized by a multiplier which is designed for low distortion and large bandwidth. The VIF signal is multiplied with the 'in phase' signal of the VIF PLL VCO.

The demodulator output signal is fed into the video preamplifier via a level shift stage with integrated low-pass filter to achieve carrier harmonics attenuation.

The output signal of the preamplifier is fed to the VIF AGC detector (see Section 8.3) and in the sound trap mode is also fed internally to the integrated sound carrier trap; see Section 8.8. The differential trap output signal is converted and amplified by the following postamplifier. The video output level at pin CVBS is 2 V (p-p).

Noise clipping is provided.

8.8 Sound carrier trap

The sound carrier trap consists of a reference filter, a phase detector and the sound trap itself.

A sound carrier reference signal is fed into the reference low-pass filter and is shifted by nominal 90 degrees. The phase detector compares the original reference signal with the signal shifted by the reference filter and produces a DC voltage by charging or discharging an integrated capacitor with a current proportional to the phase difference between both signals, respectively to the frequency error of the integrated filters. The DC voltage controls the frequency position of the reference filter and the sound trap. Thus the accurate frequency position for the different standards is set by the sound carrier reference signal.

The sound trap itself is constructed of three separate traps to realize sufficient suppression of the first and second sound carrier.

8.9 SIF amplifier

The SIF amplifier consists of three AC-coupled differential stages. Gain control is performed by emitter degeneration. The total gain control range is typical 66 dB. The differential input impedance is typical 2 k Ω in parallel with 3 pF.

8.10 SIF AGC detector

SIF gain control is performed by the detection of the SIF voltage at the output of the SIF amplifier so that a constant SIF signal is supplied to the single reference QSS mixer.

For an optimum adaption between the SIF AGC and the VIF AGC characteristics at 13 dB picture-to-sound FM carrier ratio, the internal SIF level is reduced.

The integrated AGC capacitor is charged or discharged for the generation of the required SIF gain via a comparator. An additional circuit (threshold approximately 7 dB) ensures a very fast gain reduction for a large increasing IF amplitude step.

Product data sheet

8.11 Single reference QSS mixer

With the present system high performance Hi-Fi stereo sound processing can be achieved. For a simplified application without an SIF SAW filter, the single reference QSS mixer can be switched to the intercarrier mode via pins SIF1 and SIF2; see Table 7.

The single reference QSS mixer generates the 2nd FM TV sound intercarrier signal. It is realized by a linear multiplier which multiplies the SIF amplifier output signal and the VIF PLL VCO signal which is locked to the picture carrier. In this way the QSS mixer operates as a quadrature mixer in the intercarrier mode and provides suppression of the low frequency video signals.

The QSS mixer output signal is fed internally via a high-pass and low-pass combination to the FM demodulator as well as via an operational amplifier to the QSS output pin QSSO.

8.12 FM demodulator and acquisition help circuit

The narrow-band FM PLL detector consists of:

- Gain controlled FM amplifier and AGC detector
- Narrow-band PLL.

The intercarrier signal from the single reference QSS mixer is fed to the input of an AC-coupled gain controlled amplifier with two stages. The gain controlled output signal is fed to the phase detector of the narrow-band FM PLL (FM demodulator). For good selectivity and robustness against disturbance caused by the video signal, a high linearity of the gain controlled FM amplifier and of the phase detector as well as a constant signal level are required. The gain control is done by means of an 'in phase' demodulator for the FM carrier (from the output of the FM amplifier). The demodulation output is fed into a comparator for charging or discharging the integrated AGC capacitor. This leads to a mean value AGC loop to control the gain of the FM amplifier.

The FM demodulator is realized as a narrow-band PLL with an external loop filter, which provides the necessary selectivity (bandwidth approximately 100 kHz). To achieve good selectivity, a linear phase detector and a constant input level are required. The gain controlled intercarrier signal from the FM amplifier is fed to the phase detector. The phase detector controls, via the loop filter, the integrated low radiation relaxation oscillator. The designed frequency range is from 4 MHz to 7 MHz.

The VCO within the FM PLL is phase-locked to the incoming 2nd SIF signal which is frequency modulated. The VCO control voltage is superimposed by the AF voltage. Therefore, the VCO tracks with the FM of the 2nd SIF signal. Thus, the AF voltage is present at the loop filter and is typically 5 mV (RMS) for 27 kHz FM deviation. This AF signal is fed via a buffer to the audio amplifier.

The correct locking of the PLL is supported by the digital acquisition help circuit; see Section 8.6.

www.DataSheet4U.com

8.13 Audio amplifier and mute time constant

The audio amplifier consists of two parts:

- AF preamplifier
- AF output amplifier.

The AF preamplifier used for FM sound is an operational amplifier with internal feedback, high gain and high common mode rejection. The AF voltage from the PLL demodulator is 5 mV (RMS) for a frequency deviation of 27 kHz and is amplified by 30 dB. By using a DC operating point control circuit (with external capacitor C_{AF}), the AF preamplifier is decoupled from the PLL DC voltage. The low-pass characteristic of the amplifier reduces the harmonics of the sound intercarrier signal at the AF output terminal.

For FM sound a switchable de-emphasis network (with external capacitor) is implemented between the preamplifier and the output amplifier. The de-emphasis time constant with $50 \mu s$ or $75 \mu s$ depends on the FM carrier selection via pins FM0 and FM1; see Table 5.

The AF output amplifier provides the required AF output level by a rail-to-rail output stage. A preceding stage makes use of an input selector for switching between the FM sound and mute state.

Switching to the mute state is controlled automatically, depending on the digital acquisition help circuit should the VCO of the FM PLL not be in the required frequency window. This is done by a time constant: fast for switching to the mute state and slow (typically 40 ms) for switching to the non-mute state.

Auto mute can be disabled via pin AMUTE0; see Table 6.

8.14 Internal voltage stabilizer

The band gap circuit internally generates a voltage of approximately 2.4 V, independent of the supply voltage and the temperature. A voltage regulator circuit, connected to this voltage, produces a constant voltage of 3.55 V which is used as an internal reference voltage.

8.15 Logic

The logic circuit detects the logic level at the logic ports VIF0, QSSO, FM0, FM1 and AMUTE0 and controls the internal functions; see <u>Table 4</u> to <u>Table 6</u>. In the event that all logic ports are open-circuit (high-ohmic or CMOS HIGH level) TV standard NTSC with a vision carrier frequency of 45.75 MHz, an FM sound carrier frequency of 4.5 MHz, de-emphasis with 75 μ s time constant and auto mute on is selected.

Table 4: VIF frequency selection

QSSO	VIF0	VIF frequency (MHz)
No resistor at pin	pin open-circuit	45.75
No resistor at pin	pin connected to ground	38.9
$2.2 \text{ k}\Omega$ resistor to ground at pin	pin open-circuit	58.75
$2.2~\text{k}\Omega$ resistor to ground at pin	pin connected to ground	38.0

9397 750 13417

www.DataSheet4U.com

Table 5: FM carrier frequency selection and de-emphasis settings

FM0	FM1	FM carrier frequency (MHz)	De-emphasis (μs)
Pin open-circuit	pin open-circuit	4.5	75
Pin connected to ground	pin open-circuit	5.5	50
Pin open-circuit	pin connected to ground	6.0	50
Pin connected to ground	pin connected to ground	6.5	50

Table 6: Auto mute on/off selection

AMUTE0	Auto mute
Pin open-circuit	on
Pin connected to ground	off

Table 7: Sound carrier mode

SIF1 and SIF2	Sound mode
No DC path to ground	QSS mode
One or both pins connected to ground	intercarrier mode

9. Limiting values

Table 8: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_P	supply voltage		-	5.5	V
V _n	voltage on				
	all pins except AGND, DGND and TAGC		0	V_P	V
	pin TAGC		0	8.8	V
t _{sc}	short-circuit time to ground or $V_{\mbox{\footnotesize P}}$		-	10	S
T _{stg}	storage temperature		-25	+150	°C
T _{amb}	ambient temperature				
	TDA9881TS (SSOP24)		-20	+70	°C
	TDA9881HN (HVQFN32)		-20	+85	°C
V _{esd}	electrostatic discharge voltage	human body model	<u>[1]</u> -	±4000	V
		machine model	[2] _	±400	V

^[1] Class 3A according to JESD22-A114-B.

Product data sheet

^[2] Class C according to EIA/JESD22-A115-A.

10. Thermal characteristics

Table 9: Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		
	TDA9881TS (SSOP24)		105	K/W
	TDA9881HN (HVQFN32)		40	K/W

11. Characteristics

Table 10: Characteristics

Product data sheet

 $V_P = 5~V;~T_{amb} = 25~^{\circ}C;~{\rm see}~{Table~12}~{\rm for~input~frequencies};~B/G~{\rm standard~is~used~for~the~specification}~(f_{PC} = 38.9~{\rm MHz};~f_{SC} = 33.4~{\rm MHz};~PC/SC = 13~{\rm dB};~f_{mod} = 400~{\rm Hz});~{\rm input~level~}V_{i(VIF)} = 10~{\rm mV}~(RMS)~({\rm sync~level~for~}B/G);~IF~{\rm input~from~}50~\Omega~{\rm via}$ broadband transformer 1 : 1; video modulation DSB; residual carrier for B/G is 10 %; video signal in accordance with "CCIR line 17 and line 330"; measurements taken in test circuit of Figure 21; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Supply; pin V _P)						
V_P	supply voltage		<u>[1]</u>	4.5	5.0	5.5	V
I _P	supply current			52	63	70	mA
P _{tot}	total power dissipation			-	305	385	mW
Power-on reset							
V _{P(start)}	supply voltage for start of reset	decreasing supply voltage		2.5	3.0	3.5	V
V _{P(stop)}	supply voltage for end of reset	increasing supply voltage		-	-	4.4	V
τр	time constant (R \times C) for network at pin V_P			1.2	-	-	μs
VIF amplifier;	pins VIF1 and VIF2						
$V_{i(VIF)(rms)}$	VIF input voltage sensitivity (RMS value)	−1 dB video at output		-	60	100	μV
$V_{i(max)(rms)} \\$	maximum input voltage (RMS value)	+1 dB video at output		150	190	-	mV
$V_{i(ovl)(rms)}$	overload input voltage (RMS value)		[2]	-	-	440	mV
$\Delta V_{\text{IF(int)}}$	internal IF amplitude difference between picture and sound carrier	within AGC range; $\Delta f = 5.5 \text{ MHz}$		-	0.9	-	dB
G _{VIF(cr)}	VIF gain control range	see Figure 6		60	66	-	dB
B _{VIF(-3dB)(II)}	lower limit –3 dB VIF bandwidth			-	15	-	MHz
$B_{VIF(-3dB)(uI)}$	upper limit –3 dB VIF bandwidth			-	80	-	MHz
R _{i(dif)}	differential input resistance		[3]	-	2	-	kΩ
$C_{i(dif)}$	differential input capacitance		[3]	-	3	-	pF
VI	DC input voltage			-	1.93	-	V

9397 750 13417 © Koninklijke Philips Electronics N.V. 2004. All rights reserved. Rev. 01 — 16 November 2004

13 of 42

Table 10: Characteristics ...continued

 $V_P=5~V;~T_{amb}=25~^{\circ}C;~see~Table~12~for~input~frequencies;~B/G~standard~is~used~for~the~specification~(f_{PC}=38.9~MHz;~f_{SC}=33.4~MHz;~PC/SC=13~dB;~f_{mod}=400~Hz);~input~level~V_{i(VIF)}=10~mV~(RMS)~(sync~level~for~B/G);~IF~input~from~50~\Omega~via~broadband~transformer~1:~1;~video~modulation~DSB;~residual~carrier~for~B/G~is~10~%;~video~signal~in~accordance~with~"CCIR~line~17~and~line~330";~measurements~taken~in~test~circuit~of~Figure~21;~unless~otherwise~specified.$

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
FPLL and true	e synchronous video demo	dulator [4]				
f _{VCO(max)}	maximum oscillator frequency for carrier regeneration	f = 2f _{PC}	120	140	-	MHz
f_{VIF}	vision carrier operating	see Table 4	-	38.0	-	MHz
	frequencies		-	38.9	-	MHz
			-	45.75	-	MHz
			-	58.75	-	MHz
Δf_{VIF}	VIF frequency window of digital acquisition help	related to f _{VIF} ; see <u>Figure 9</u>	-	±2.3	-	MHz
t _{acq}	acquisition time	BL = 70 kHz	<u>[5]</u> _	-	30	ms
V _{i(lock)(rms)}	input voltage sensitivity for PLL to be locked (RMS value)	measured on pins VIF1 and VIF2; maximum IF gain	-	50	100	μV
T _{cy(DAH)}	cycle time of digital acquisition help		-	64	-	μs
K _{O(VIF)}	VIF VCO steepness	definition: $\Delta f_{VIF}/\Delta V_{VPLL}$	-	20	-	MHz/\
$K_{D(VIF)}$	VIF phase detector steepness	definition: $\Delta I_{VPLL}/\Delta \phi_{VIF}$	-	23	-	μA/rad
Video output	2 V; pin CVBS; sound carri	er on				
$V_{o(p-p)}$	video output voltage (peak-to-peak value)	see Figure 4	1.7	2.0	2.3	V
V/S	ratio between video (black-to-white) and sync level		1.90	2.33	3.00	
V _{sync}	sync voltage level		1.0	1.2	1.4	V
$V_{clip(u)}$	upper video clipping voltage level		V _P – 1.1	V _P – 1	-	V
$V_{clip(I)}$	lower video clipping voltage level		-	0.7	0.9	V
R _o	output resistance		[3]	-	30	Ω
I _{bias(int)}	internal DC bias current for emitter-follower		1.5	2.0	-	mA
I _{o(sink)(max)}	maximum AC and DC output sink current		1	-	-	mA
I _{o(source)(max)}	maximum AC and DC output source current		3.9	-	-	mA
$\Delta V_{o(CVBS)}$	deviation of CVBS output	50 dB gain control	-	-	0.5	dB
	voltage	30 dB gain control	-	-	0.1	dB
$\Delta V_{o(bl)}$	black level tilt		-	-	2	%
G _{dif}	differential gain	"CCIR 330"; B/G standard	[6] -	-	5	%

9397 750 13417

© Koninklijke Philips Electronics N.V. 2004. All rights reserved.

14 of 42

 Table 10:
 Characteristics ...continued

S/N _{W(V(deo)} weighted signal-to-noise ratio weighted in accordance with "CCIR 567"; see Figure 10 I' 47	deg	Max	Тур	Min		Conditions	Parameter	Symbol
Tatio With "CCIR 667"; see Figure 10 If a part of the signal-to-noise ratio If a part of the signal part of the s	acg	4	2	-		"CCIR 330"	differential phase	Pdif
Signal-to-noise ratio Sign	dB	-	-	55	<u>[7]</u>	with "CCIR 567";	-	S/N _{W(video)}
attenuation at 'blue' f = 1.1 MHz	dB	-	-	47	[7]		•	S/N _{UW(video)}
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$					[8]	see Figure 11		$\alpha_{IM(blue)}$
$ \frac{\alpha_{\text{IM}/\text{yellow}}}{\text{attenuation at 'yellow'}} = \frac{\text{see Figure 11}}{\text{f = 1.1 MHz}} = \frac{19}{60} = \frac{66}{66} = \frac{1}{60} = 1$	dB	-	64	58		f = 1.1 MHz	attenuation at 'blue'	
attenuation at 'yellow'	dB	-	64	58		f = 3.3 MHz		
$f = 3.3 \text{MHz} \qquad 59 \qquad 65 \qquad - \qquad \\ f = 3.3 \text{MHz} \qquad 59 \qquad 65 \qquad - \qquad \\ \text{Call MS value} \qquad \qquad$					[8]	see Figure 11		$\alpha_{IM(yellow)}$
$ \frac{\Delta V_{r(PC)(rms)}}{\Delta V_{r(PC)(rms)}} \begin{array}{c} \text{residual picture carrier} \\ \text{(RMS value)} \\ \end{array}{c} \begin{array}{c} \text{fundamental wave and} \\ \text{harmonics} \\ \end{array}{c} \begin{array}{c} -2 \\ \text{Signal harmonics} \\ \end{array}{c} \begin{array}{c} C_L < 20 \text{ pF; } R_L > 1 \text{ k}\Omega; \\ \text{AC load} \\ \end{array}{c} \begin{array}{c} 9 \\ \text{35} \\ \end{array}{c} \begin{array}{c} 40 \\ \text{O} \\ \end{array}{c} \begin{array}{c} -2 \\ \text{Signal harmonics} \\ \end{array}{c} \begin{array}{c} C_L < 20 \text{ pF; } R_L > 1 \text{ k}\Omega; \\ \text{AC load} \\ \end{array}{c} \begin{array}{c} 9 \\ \text{35} \\ \end{array}{c} \begin{array}{c} 40 \\ \text{O} \\ \end{array}{c} \begin{array}{c} -2 \\ \text{Signal harmonics} \\ \end{array}{c} \begin{array}{c} -2 \\ \text{AC load} \\ \end{array}{c} \begin{array}{c} 100 \\ \text{40} \\ \end{array}{c} \begin{array}{c} -2 \\ \text{Color} \\ \end{array}{c} \begin{array}{c} -2 \\ Colo$	dB	-	66	60		f = 1.1 MHz	attenuation at 'yellow'	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	dB	-	65	59		f = 3.3 MHz		
α _{spur} signal harmonics AC load α _{spur} suppression of spurious elements [10] 40 - - PSRR _{CVBS} power supply ripple rejection at pin CVBS see Figure 5 [11] 20 25 - M/N standard inclusive Korea; see Figure 12 Elements 8 - - B _V (-3dB)(trap) -3 dB video bandwidth including sound carrier trap ftrap = 4.5 MHz 12] 3.95 4.05 - α _{SC1} attenuation at first sound carrier f = 4.5 MHz 26 36 - α _{SC1} (60kHz) attenuation at first sound carrier fs _{C1} ± 60 kHz f = 4.5 MHz 20 27 - α _{SC2} attenuation at second sound carrier fs _{C2} ± 60 kHz f = 4.724 MHz 14 21 - α _{SC2} (60kHz) attenuation at second sound carrier fs _{C2} ± 60 kHz f = 3.58 MHz; 110 180 250 B/G standard; see Figure 14 B _V (-3dB)(trap) -3 dB video bandwidth including sound carrier trap f _{Trap} = 5.5 MHz 12 4.90 5.00 - α _{SC1} attenuation at first sound carrier f = 5.5 MHz 2	mV	5	2	-				$\Delta V_{r(PC)(rms)}$
PSRR _{CVBS} power supply ripple rejection at pin CVBS see Figure 5 M/N standard inclusive Korea; see Figure 12 $B_{V(-3dB)(trap)}$ -3 dB video bandwidth including sound carrier trap α_{SC1} attenuation at first sound carrier $\alpha_{SC1(60kHz)}$ attenuation at second sound carrier $\alpha_{SC1(60kHz)}$ attenuation at second sound carrier $\alpha_{SC2(60kHz)}$ attenuation at second sound carrier $\alpha_{SC2(60kHz)}$ attenuation at second $\alpha_{SC2(60kHz)}$ attenuation $\alpha_{SC2(60kHz)}$ α_{S	dB	-	40	35	[9]			α_{H}
rejection at pin CVBS see Figure 5 M/N standard inclusive Korea; see Figure 12 $B_{V(-3dB)(trap)}$ $\stackrel{-3}{\sim} 3dB$ video bandwidth including sound carrier trap α_{SC1} attenuation at first sound carrier fire $\frac{12}{3.95}$	dB	-	-	40	[10]			$lpha_{\sf spur}$
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	dB	-	25	20	[11]			PSRR _{CVBS}
including sound carrier trap $\alpha_{SC1} = \text{attenuation at first sound carrier} \\ \alpha_{SC1} = \text{attenuation at first sound carrier} \\ \alpha_{SC1(60kHz)} = \text{attenuation at first sound carrier } \\ \alpha_{SC2} = \text{attenuation at second sound carrier} \\ \alpha_{SC2} = \text{attenuation at carrier} \\ \alpha_{SC3} = \text{attenuation at first sound for the sound sound carrier} \\ \alpha_{SC1} = attenuation at first sound for the sound$						2	nclusive Korea; see Figure 1	M/N standard in
$ carrier \\ \alpha_{SC1(60kHz)} \text{attenuation at first sound} f = 4.5 \text{ MHz} \\ \alpha_{SC2} \text{attenuation at second} f = 4.724 \text{ MHz} \\ sound carrier \\ \alpha_{SC2(60kHz)} \text{attenuation at second} f = 4.724 \text{ MHz} \\ sound carrier \\ f_{SC2} \pm 60 \text{ kHz} \\ t_{d(g)(cc)} \text{group delay at color} \\ carrier frequency \text{see Figure 13} \\ B/G \text{ standard; see Figure 14} \\ B_{V(-3dB)(trap)} -3 \text{ dB video bandwidth} \\ including sound carrier \\ trap \\ \alpha_{SC1} \text{attenuation at first sound} f = 5.5 \text{ MHz} \\ \alpha_{SC1} \text{attenuation at first sound} f = 5.5 \text{ MHz} \\ attenuation at first sound} f = 5.5 $	MHz	-	4.05	3.95	[12]	$f_{trap} = 4.5 \text{ MHz}$	including sound carrier	B _{v(-3dB)(trap)}
$ carrier f_{SC1} \pm 60 \text{ kHz} $	dB	-	36	26		f = 4.5 MHz		$lpha_{ m SC1}$
	dB	-	27	20		f = 4.5 MHz		αSC1(60kHz)
$sound carrier \\ f_{SC2} \pm 60 \text{ kHz} \\ t_{d(g)(cc)} \qquad group \text{ delay at color} \\ carrier frequency} \qquad f = 3.58 \text{ MHz}; \\ see Figure 13 \\ \hline B/G \text{ standard; see } Figure 14 \\ B_{v(-3dB)(trap)} \qquad -3 \text{ dB video bandwidth} \\ including sound carrier \\ trap \\ \hline \alpha_{SC1} \qquad attenuation at first sound } f = 5.5 \text{ MHz} \\ carrier \\ \hline \alpha_{SC1(60kHz)} \qquad attenuation at first sound } f = 5.5 \text{ MHz} \\ \hline 26 \qquad 36 \qquad - \\ \hline 20 \qquad 30 \qquad - \\ \hline$	dB	-	27	20		f = 4.724 MHz		α_{SC2}
carrier frequency see Figure 13 B/G standard; see Figure 14 B _{v(-3dB)(trap)} -3 dB video bandwidth including sound carrier trap α_{SC1} attenuation at first sound $\alpha_{SC1(60kHz)}$ attenuation at first sound $\alpha_{SC1(60kHz)}$ attenuation at first sound $\alpha_{SC3(60kHz)}$	dB	-	21	14		f = 4.724 MHz	sound carrier	αsc2(60kHz)
$B_{V(-3dB)(trap)} = -3 \text{ dB video bandwidth including sound carrier trap} = 5.5 \text{ MHz} = 5.5 $	ns	250	180	110			0 ,	t _{d(g)(cc)}
including sound carrier trap $\alpha_{SC1} = \begin{array}{ccccccccccccccccccccccccccccccccccc$							see Figure 14	B/G standard; s
carrier $\alpha_{SC1(60kHz)}$ attenuation at first sound f = 5.5 MHz 20 30 -	MHz	-	5.00	4.90	[12]	$f_{trap} = 5.5 \text{ MHz}$	including sound carrier	B _{v(-3dB)(trap)}
~ · · · · · · · · · · · · · · · · · · ·	dB	-	36	26		f = 5.5 MHz		α_{SC1}
carrier f _{SC1} ± 60 kHz	dB	-	30	20		f = 5.5 MHz	attenuation at first sound carrier $f_{SC1}\pm60~\text{kHz}$	αSC1(60kHz)

Table 10: Characteristics ...continued

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
α_{SC2}	attenuation at second sound carrier	f = 5.742 MHz		20	27	-	dB
$\alpha_{\text{SC2(60kHz)}}$	attenuation at second sound carrier $f_{SC2} \pm 60 \text{ kHz}$	f = 5.742 MHz		14	21	-	dB
$t_{d(g)(cc)}$	group delay at color carrier frequency	f = 4.43 MHz; see <u>Figure 15</u>		110	180	250	ns
I standard; see	Figure 16						
B _{v(-3dB)(trap)}	 –3 dB video bandwidth including sound carrier trap 	$f_{trap} = 6.0 \text{ MHz}$	[12]	5.40	5.50	-	MHz
α_{SC1}	attenuation at first sound carrier	f = 6.0 MHz		26	32	-	dB
α _{SC1(60kHz)}	attenuation at first sound carrier $f_{SC1} \pm 60 \text{ kHz}$	f = 6.0 MHz		20	26	-	dB
α _{SC2}	attenuation at second sound carrier	f = 6.55 MHz		12	18	-	dB
α _{SC2(60kHz)}	attenuation at second sound carrier $f_{SC2} \pm 60 \text{ kHz}$	f = 6.55 MHz		10	15	-	dB
$t_{d(g)(cc)}$	group delay at color carrier frequency	f = 4.43 MHz		-	90	160	ns
D/K standard; s	see <u>Figure 17</u>						
B _{v(-3dB)(trap)}	–3 dB video bandwidth including sound carrier trap	$f_{trap} = 6.5 \text{ MHz}$	[12]	5.50	5.95	-	MHz
α _{SC1}	attenuation at first sound carrier	f = 6.5 MHz		26	32	-	dB
α _{SC1(60kHz)}	attenuation at first sound carrier $f_{SC1} \pm 60 \text{ kHz}$	f = 6.5 MHz		20	26	-	dB
α_{SC2}	attenuation at second sound carrier	f = 6.742 MHz		18	24	-	dB
α _{SC2(60kHz)}	attenuation at second sound carrier $f_{SC2} \pm 60 \text{ kHz}$	f = 6.742 MHz		13	18	-	dB
$t_{d(g)(cc)}$	group delay at color carrier frequency	f = 4.28 MHz		-	60	130	ns
VIF AGC							
t _{resp(inc)}	AGC response time to an increasing VIF step	20 dB	[13]	-	4	-	ms
t _{resp(dec)}	AGC response time to a decreasing VIF step	20 dB	[13]	-	3	-	ms

Table 10: Characteristics ...continued

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
CR _{stps}	control steepness	definition: $\Delta G_{VIF}/\Delta V_{VAGC}$; $V_{VAGC} = 2 \text{ V to 3 V}$	-	-80	-	dB/V
Pin VAGC						
V_{VAGC}	gain control voltage range	see Figure 6	0.8	-	3.5	V
I _{o(sink)(max)}	maximum output sink current		-	-	10	μΑ
I _{o(source)(max)}	maximum output source current		-	-	10	μΑ
Tuner AGC; pin	TAGC; see Figure 6 to Fi	gure 8				
Vi(VIF)(start1)(rms)	VIF input signal voltage for minimum starting point of tuner takeover at pins VIF1 and VIF2 (RMS value)	I_{TAGC} = 120 μA; R_{TOP} = 22 kΩ	-	2	5	mV
V _{i(VIF)} (start2)(rms)	VIF input signal voltage for maximum starting point of tuner takeover at pins VIF1 and VIF2 (RMS value)	I_{TAGC} = 120 μA; R_{TOP} = 0 Ω	45	90	-	mV
QV_TOP	tuner takeover point accuracy	I_{TAGC} = 120 μA; R_{TOP} = 10 kΩ	7	17	43	mV
$\Delta QV_{TOP}/\Delta T$	takeover point variation with temperature	I _{TAGC} = 120 μA	-	0.03	0.07	dB/K
Vo	permissible output voltage	from external source	-	-	8.8	V
V _{sat}	saturation voltage	I _{TAGC} = 450 μA	-	-	0.5	V
I _{sink}	sink current	no tuner gain reduction; V _{TAGC} = 8.8 V	-	-	0.75	μΑ
		maximum tuner gain reduction; V _{TAGC} = 1 V	450	600	750	μΑ
ΔG_IF	IF slip by automatic gain control	tuner gain current from 20 % to 80 %	3	5	8	dB
AFC circuit; pin	AFC; see <u>Figure 9 [14] [15]</u>					
AFC _{stps}	AFC control steepness	definition: $\Delta I_{AFC}/\Delta f_{VIF}$	0.85	1.05	1.25	μΑ/kHz
$Qf_{VIF(a)}$	analog accuracy of AFC circuit	I _{AFC} = 0 A; f _{REF} = 4 MHz	-20	-	+20	kHz
V _{sat(uI)}	upper limit saturation voltage		$V_P - 0.6$	$V_P - 0.3$	-	V
V _{sat(II)}	lower limit saturation voltage		-	0.3	0.6	V
I _{o(source)}	output source current		160	200	240	μΑ
I _{o(sink)}	output sink current		160	200	240	μΑ
9397 750 13417				© Koninklijke Phil	ips Electronics N.V.	2004. All rights reserved
Product data shee	<u></u>	Rev. 01 — 16 November 20	004			17 of 42

Table 10: Characteristics ...continued

 $V_P=5~V;~T_{amb}=25~^{\circ}C;~see~Table~12~for~input~frequencies;~B/G~standard~is~used~for~the~specification~(f_{PC}=38.9~MHz;~f_{SC}=33.4~MHz;~PC/SC=13~dB;~f_{mod}=400~Hz);~input~level~V_{i(VIF)}=10~mV~(RMS)~(sync~level~for~B/G);~IF~input~from~50~\Omega~via~broadband~transformer~1:~1;~video~modulation~DSB;~residual~carrier~for~B/G~is~10~%;~video~signal~in~accordance~with~"CCIR~line~17~and~line~330";~measurements~taken~in~test~circuit~of~Figure~21;~unless~otherwise~specified.$

Symbol	Parameter	meter Conditions Mi				Max	Unit
SIF amplifier;	pins SIF1 and SIF2						
V _{i(SIF)(rms)}	SIF input voltage sensitivity (RMS value)	-3 dB at intercarrier output pin QSSO		-	30	70	μV
$V_{i(max)(rms)}$	maximum input voltage (RMS value)	1 dB at intercarrier output pin QSSO		50	70	-	mV
$V_{i(ovl)(rms)}$	overload input voltage (RMS value)		[2]	-	-	320	mV
G _{SIF(cr)}	SIF gain control range	see Figure 8		60	66	-	dB
B _{SIF(-3dB)(II)}	lower limit –3 dB SIF bandwidth			-	15	-	MHz
B _{SIF(-3dB)(uI)}	upper limit –3 dB SIF bandwidth			-	80	-	MHz
$R_{i(dif)}$	differential input resistance		[3]	-	2	-	kΩ
$C_{i(dif)}$	differential input capacitance		[3]	-	3	-	pF
VI	DC input voltage			-	1.93	-	V
SIF AGC dete	ctor						
t _{resp}	AGC response time to an	increasing		-	8	-	ms
	increasing or decreasing SIF step of 20 dB	decreasing		-	25	-	ms
Single referen	nce QSS intercarrier mixer;	pin QSSO					
V _{o(intc)(rms)}	IF intercarrier output level (RMS value)	QSS mode; SC ₁ ; SC ₂ off		90	140	210	mV
		intercarrier mode; PC/SC ₁ = 20 dB; SC ₂ off	[16]	-	75	-	mV
B _{intc(-3dB)(ul)}	upper limit –3 dB intercarrier bandwidth			12	15	-	MHz
$\Delta V_{r(SC)(rms)}$	residual sound carrier (RMS value)	fundamental wave and harmonics		-	2	5	mV
$\Delta V_{r(PC)(rms)}$	residual picture carrier (RMS value)	fundamental wave and harmonics		-	2	5	mV
R_o	output resistance		[3]	-	-	30	Ω
Vo	DC output voltage			-	2	-	V
I _{bias(int)}	internal DC bias current for emitter follower			0.9	1.3	-	mA
I _{o(sink)(max)}	maximum AC output sink current			0.6	0.8	-	mA
I _{o(source)(max)}	maximum AC output source current			0.6	0.8	-	mA
I _{o(source)}	DC output source current	QSSO = 0; see <u>Table 4</u>	[17]	0.75	0.93	1.20	mA

9397 750 13417

Table 10: Characteristics ...continued

Min	Тур	Max	Unit
3.2	-	320	mV
-	-	2	mV
-	-	2.3	mV
-	4.5	-	MHz
-	5.5	-	MHz
•	6.0	-	MHz
-	6.5	-	MHz
400	500	600	mV
430	540	650	mV
1.3	1.4	-	V
-	3 × 10 ⁻³	7 × 10 ⁻³	dB/K
•	0.15	0.50	%
-	-	±55	kHz
80	100	-	kHz
52	56	-	dB
50	56	-	dB
-	-	2	mV
40	46	-	dB
40			
		© Koninklijke Ph	© Koninklijke Philips Electronics N.V. 2

Table 10: Characteristics ... continued

 $V_P=5~V;~T_{amb}=25~^\circ C;~see~Table~12~for~input~frequencies;~B/G~standard~is~used~for~the~specification~(f_{PC}=38.9~MHz;~f_{SC}=33.4~MHz;~PC/SC=13~dB;~f_{mod}=400~Hz);~input~level~V_{i(VIF)}=10~mV~(RMS)~(sync~level~for~B/G);~IF~input~from~50~\Omega~via~broadband~transformer~1:~1;~video~modulation~DSB;~residual~carrier~for~B/G~is~10~%;~video~signal~in~accordance~with~"CCIR~line~17~and~line~330";~measurements~taken~in~test~circuit~of~Figure~21;~unless~otherwise~specified.$

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
PSRR _{FM}	power supply ripple rejection	f _{ripple} = 70 Hz; see <u>Figure 5</u>	14	20	-	dB
FM PLL filter; pir	n FMPLL					
V_{loop}	DC loop voltage		1.5	-	3.3	V
lo(source)(PD)(max)	maximum phase detector output source current		-	60	-	μΑ
$I_{o(sink)(PD)(max)}$	maximum phase detector output sink current		-	60	-	μΑ
I _{o(source)(DAH)}	output source current of digital acquisition help		-	55	-	μΑ
I _{o(sink)(DAH)}	output sink current of digital acquisition help		-	55	-	μΑ
t _{W(DAH)}	pulse width of digital acquisition help current		-	16	-	μs
T _{cy(DAH)}	cycle time of digital acquisition help		-	64	-	μs
K _{O(FM)}	VCO steepness	definition: $\Delta f_{FM}/\Delta V_{FMPLL}$	-	3.3	-	MHz/V
$K_{D(FM)}$	phase detector steepness	definition: $\Delta I_{\text{FMPLL}}/\Delta \phi_{\text{FM}}$	-	4	-	μA/rad
Audio amplifier						
De-emphasis ne	twork; pin DEEM					
R _o	output resistance	50 μs de-emphasis; see <u>Table 5</u>	4.4	5.0	5.6	kΩ
		75 μs de-emphasis; see <u>Table 5</u>	6.6	7.5	8.4	kΩ
$V_{AF(rms)}$	audio signal (RMS value)	$f_{AF} = 400 \text{ Hz};$ $V_{FMSO} = 500 \text{ mV}$	-	170	-	mV
Vo	DC output voltage		-	2.37	-	V
AF decoupling; p	oin AFD					
$V_{ m dec}$	DC decoupling voltage	dependent on f _{FM} intercarrier frequency	1.5	-	3.3	V
l _L	leakage current	$\Delta V_{O(FMSO)} < \pm 50 \text{ mV}$	-	-	±25	nA
I _{ch(max)}	maximum charge current		1.15	1.50	1.85	μΑ
I _{dch(max)}	maximum discharge current		1.15	1.50	1.85	μΑ
FM sound outpu	t; pin FMSO					
R _o	output resistance		[3] _	-	300	Ω
V _{O(FMSO)}	DC output voltage		-	2.37	-	V
R_L	load resistance	AC-coupled	10	-	-	kΩ
R _{L(DC)}	DC load resistance		100	-	-	kΩ
C _L	load capacitance		-	-	1.5	nF

9397 750 13417

Table 10: Characteristics ...continued

 $V_P=5~V;~T_{amb}=25~^{\circ}C;~see~Table~12~for~input~frequencies;~B/G~standard~is~used~for~the~specification~(f_{PC}=38.9~MHz;~f_{SC}=33.4~MHz;~PC/SC=13~dB;~f_{mod}=400~Hz);~input~level~V_{i(VIF)}=10~mV~(RMS)~(sync~level~for~B/G);~IF~input~from~50~\Omega~via~broadband~transformer~1:~1;~video~modulation~DSB;~residual~carrier~for~B/G~is~10~%;~video~signal~in~accordance~with~"CCIR~line~17~and~line~330";~measurements~taken~in~test~circuit~of~Figure~21;~unless~otherwise~specified.$

Symbol	Parameter	Conditions	Mi	n Typ	Max	Unit
B _{AF(-3dB)(ul)}	upper limit –3 dB AF bandwidth of audio amplifier		15	0 -	-	kHz
B _{AF(-3dB)(II)}	lower limit –3 dB AF bandwidth of audio amplifier		[20] _	-	20	Hz
α_{mute}	mute attenuation of AF signal	via pin AMUTE0; see <u>Table 6</u>	70	75	-	dB
ΔV_{jump}	DC jump voltage for switching AF output to mute state or vice versa	activated by digital acquisition help; auto mute on; see Table 6	-	±50	±150	mV
FM operation	[21] [23]					
Intercarrier AF	performance [24]					
S/N _W	weighted signal-to-noise ratio	PC/SC ratio is 21 dB to 27 dB at pins VIF1 and VIF2				
		black picture	49	-	-	dB
		white picture	45	-	-	dB
		6 kHz sine wave (black-to-white modulation)	40	-	-	dB
		sound carrier subharmonics; f = 2.75 MHz ± 3 kHz	35	-	-	dB
Single referen	ce QSS AF performance [25] [2	26]				
S/N _{W(SC1)}	weighted signal-to-noise ratio for SC ₁	VIF input sound carrier suppression: PC/SC ₁ ratio at pins VIF1 and VIF2 > 40 dB				
		black picture	51	-	-	dB
		white picture	48	-	-	dB
		6 kHz sine wave (black-to-white modulation)	42	-	-	dB
		250 kHz square wave (black-to-white modulation)	40	-	-	dB
		sound carrier subharmonics; f = 2.75 MHz ± 3 kHz	43	-	-	dB
		sound carrier subharmonics; f = 2.87 MHz ± 3 kHz	44	. -	-	dB

Product data sheet

Table 10: Characteristics ... continued

 $V_P=5~V;~T_{amb}=25~^\circ C;~see~ {Table~12}~for~input~frequencies;~B/G~standard~is~used~for~the~specification~(f_{PC}=38.9~MHz;~f_{SC}=33.4~MHz;~PC/SC=13~dB;~f_{mod}=400~Hz);~input~level~V_{i(VIF)}=10~mV~(RMS)~(sync~level~for~B/G);~IF~input~from~50~\Omega~via~broadband~transformer~1:~1;~video~modulation~DSB;~residual~carrier~for~B/G~is~10~%;~video~signal~in~accordance~with~"CCIR~line~17~and~line~330";~measurements~taken~in~test~circuit~of~Figure~21;~unless~otherwise~specified.$

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
S/N _{W(SC2)}	weighted signal-to-noise ratio for ${ m SC}_2$	VIF input sound carrier suppression: PC/SC ₂ ratio at pins VIF1 and VIF2 > 40 dB					
		black picture		46	-	-	dB
		white picture		45	-	-	dB
		6 kHz sine wave (black-to-white modulation)		41	-	-	dB
		250 kHz square wave (black-to-white modulation)		29	-	-	dB
		sound carrier subharmonics; f = 2.75 MHz ± 3 kHz		42	-	-	dB
		sound carrier subharmonics; f = 2.87 MHz ± 3 kHz		43	-	-	dB
Reference fr	equency input; pin REF						
VI	DC input voltage			2.3	2.6	2.9	V
R _i	input resistance		[3]	-	5	-	kΩ
R _{xtal}	resonance resistance of crystal	operation as crystal oscillator		-	-	200	Ω
C _x	pull-up or pull-down capacitance		[27]	-	-	-	pF
f _{ref}	reference signal frequency		[28]	-	4	-	MHz
Δf_{ref}	tolerance of reference signal frequency		[15]	-	-	±0.1	%
V _{ref(rms)}	reference signal voltage (RMS value)	operation as input terminal		80	-	400	mV
R _{o(ref)}	output resistance of reference signal source			-	-	4.7	kΩ
C _K	decoupling capacitance to external reference signal source	operation as input terminal		22	100	-	pF
Logic; pins l	FM1, FM0, VIF0 and AMUTEO); see <u>Table 4</u> to <u>Table 6</u>					
Vi	input voltage	for LOW level		0	-	8.0	V
		for HIGH level		2.5	-	V_P	V
V _{i(open)}	free-running voltage	pin open-circuit; $I_i < 0.1 \mu A$		-	V_P	-	V
R _i	internal pull-up resistance			37.5	-	62.5	kΩ

[1] Values of video and sound parameters can be decreased at V_P = 4.5 V.

9397 750 13417

- [2] Level headroom for input level jumps during gain control setting.
- [3] This parameter is not tested during the production and is only given as application information for designing the receiver circuit.
- [4] Loop bandwidth BL = 70 kHz (damping factor d = 1.9; calculated with sync level within gain control range). Calculation of the VIF PLL filter can be done by use of the following formula:

$$BL_{-3dB} = \frac{1}{2\pi} K_O K_D R$$
, valid for d \geq 1.2

$$d = \frac{1}{2} R \sqrt{K_O K_D C} \,,$$

where:

 ${
m K_O}$ is the VCO steepness $\left(rac{{
m rad}}{V}\right)$ or $\left(2\pirac{{
m Hz}}{V}\right)$; ${
m K_D}$ is the phase detector steepness $\left(rac{{
m \mu}A}{{
m rad}}\right)$;

R is the loop resistor; C is the loop capacitor; BL_3dB is the loop bandwidth for -3 dB; d is the damping factor.

- [5] $V_{i(V|F)} = 10 \text{ mV (RMS)}$; $\Delta f = 1 \text{ MHz (VCO frequency offset related to picture carrier frequency)}$; white picture video modulation.
- [6] Condition: luminance range (5 steps) from 0 % to 100 %.
- [7] S/N_{W(video)} is the ratio of black-to-white amplitude to the black level noise voltage (RMS value measured on pin CVBS). B = 5 MHz (B/G, I and D/K standard). Noise analyzer setting: 200 kHz high-pass and SC-trap switched on.
- [8] The intermodulation figures are defined for:
 - a) f = 1.1 MHz (referenced to black and white signal) as $\alpha_{IM} = 20 \log \left(\frac{V_0 \text{ at } 4.4 \text{ MHz}}{V_0 \text{ at } 1.1 \text{ MHz}} \right) + 3.6 \text{ dB}$
 - b) f = 3.3 MHz (referenced to color carrier) as $\alpha_{IM} = 20 log \left(\frac{V_0 \text{ at } 4.4 \text{ MHz}}{V_0 \text{ at } 3.3 \text{ MHz}} \right)$
- [9] Modulation Vestigial Side-Band (VSB); sound carrier off; f_{video} > 0.5 MHz. Measurements taken with SAW filter M1963M (sound shelf: 20 dB); loop bandwidth BL = 70 kHz.
- [10] Sound carrier on; f_{video} = 10 kHz to 10 MHz. Measurements taken with SAW filter M1963M (sound shelf: 20 dB); loop bandwidth BL = 70 kHz.
- [11] Conditions: video signal, grey level and negative modulation.
- [12] AC load; $C_L < 20 \text{ pF}$ and $R_L > 1 \text{ k}\Omega$. The sound carrier frequencies (depending on TV standard) are attenuated by the integrated sound carrier traps (see Figure 12 to Figure 17; |H(s)| is the absolute value of transfer function).
- [13] The response time is valid for a VIF input level range from 200 μV to 70 mV.
- [14] To match the AFC output signal to different tuning systems a current source output is provided. The test circuit is given in <u>Figure 9</u>. The AFC slope (voltage per frequency) can be changed by resistors R1 and R2.
- [15] The tolerance of the reference frequency determines the accuracy of the VIF AFC, FM demodulator center frequency and maximum FM deviation.
- [16] The intercarrier output signal at pin QSSO can be calculated by the following formula taking into account the internal video signal with 1.1 V (p-p) as a reference:

$$V_{\text{o(intc)}} = 1.1 \text{ V (p-p)} \times \frac{\frac{V_{i(SC)}}{V_{i(PC)}} (dB) + 6 \text{ dB} \pm 3 \text{ dB}}{20}$$
 (RMS)

where: $\frac{1}{2\sqrt{2}}$ is the correction term for RMS value, $\frac{V_{i(SC)}}{V_{i(PC)}}(dB)$ is the sound-to-picture carrier ratio at pins VIF1 and VIF2 in dB, 6 dB is

the correction term of internal circuitry and ± 3 dB is the tolerance of video output and intercarrier output Vo(intc)(rms)-

- [17] To detect a logical 1 at pin QSSO, no DC load at pin QSSO is allowed. QSSO = 0 will be done by the application of a 2.2 k Ω resistor between pin QSSO and ground.
- [18] SIF input level is 10 mV (RMS); VIF input level is 10 mV (RMS) unmodulated.
- [19] Measured with an FM deviation of 25 kHz and the typical AF output voltage of 500 mV (RMS). For handling a frequency deviation of more than 55 kHz, the AF output signal has to be reduced in order to avoid clipping (THD < 1.5 %) by means of a resistor R_x with external application at pin AFD (see Figure 20 and Figure 21).
- [20] The lower limit of the audio bandwidth depends on the value of the capacitor at pin AFD. A value of $C_{AF} = 470$ nF leads to $f_{AF(-3dB)} \approx 20$ Hz and $C_{AF} = 220$ nF leads to $f_{AF(-3dB)} \approx 40$ Hz.

9397 750 13417

- [21] For all S/N measurements the used VIF modulator has to meet the following specifications:
 - a) Incidental phase modulation for black-to-white jump less than 0.5 degrees.
 - b) QSS AF performance, measured with the television demodulator AMF2 (audio output, weighted S/N ratio) better than 60 dB (at deviation 27 kHz) for 6 kHz sine wave black-to-white video modulation.
 - c) Picture-to-sound carrier ratio PC/SC₁ = 13 dB (transmitter).
- [22] Calculation of the loop filter can be done approximately by use of the following formulae:

$$f_o = \frac{1}{2\pi} \sqrt{\frac{K_O K_D}{C_P}}$$

$$\vartheta = \frac{1}{2R \sqrt{K_O K_D C_P}}$$

$$BL_{-3dB} = f_o(1.55 - \vartheta^2)$$

The formulae are only valid under the following conditions: $\vartheta \leq 1$ and $C_S > 5C_P$

where: K_{O} is the VCO steepness $\left(\frac{rad}{V}\right)$ or $\left(2\pi\frac{Hz}{V}\right)$; K_{D} is the phase detector steepness $\left(\frac{\mu A}{rad}\right)$; R is the loop resistor; C_{S} is the series

capacitor; C_P is the parallel capacitor; f_o is the natural frequency of PLL; BL_{-3dB} is the loop bandwidth for -3 dB; ϑ is the damping factor. For examples, see Table 11.

- [23] The PC/SC ratio is calculated as the addition of TV transmitter PC/SC₁ ratio and SAW filter PC/SC₁ ratio. This PC/SC ratio is necessary to achieve the S/N_W values as noted. A different PC/SC ratio will change these values.
- [24] Measurements taken with SAW filter G1984 (Siemens) for vision and sound IF (sound shelf: 14 dB). Picture-to-sound carrier ratio of transmitter PC/SC = 13 dB. Input level on pins VIF1 and VIF2 of V_{i(SIF)} = 10 mV (RMS) sync level, 27 kHz FM deviation for sound carrier, f_{AF} = 400 Hz. Measurements in accordance with "CCIR 468". De-emphasis is 50 μs.
- [25] The QSS signal output on pin QSSO is analyzed by a test demodulator TDA9820. The S/N ratio of this device is more than 60 dB, related to a deviation of ± 27 kHz, in accordance with "CCIR 468".
- [26] Measurements taken with SAW filter G3962 for vision IF (suppressed sound carrier) and K9350 for sound IF (suppressed picture carrier). Input level V_{i(SIF)} = 10 mV (RMS), 27 kHz (54 % FM deviation).
- [27] The value of C_x determines the accuracy of the resonance frequency of the crystal. It depends on the used type of crystal.
- [28] Pin REF is able to operate as a 1-pin crystal oscillator input as well as an external reference signal input, e.g. from the tuning system.

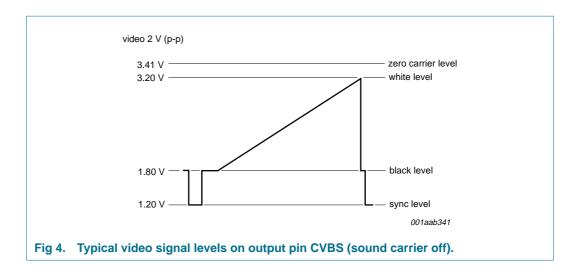
Table 11: Examples to the FM PLL filter

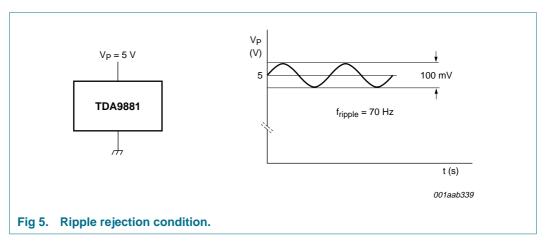
BL _{-3dB} (kHz)	C _S (nF)	C _P (pF)	R (k Ω)	ϑ
100	10	390	5.6	0.5
160	10	150	9.1	0.5

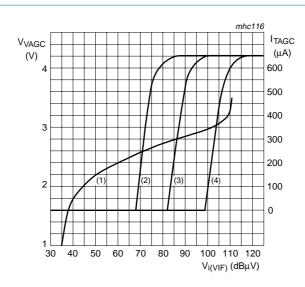
Table 12: Input frequencies and carrier ratios

Description	Symbol	B/G standard	M/N standard	Unit	
VIF carrier	f_{PC}	38.9	45.75 or 58.75	MHz	
SIF carrier	f _{SC1}	33.4	41.25 or 54.25	MHz	
	f _{SC2}	33.158	-	MHz	
Picture-to-sound	SC ₁	13	7	dB	
carrier ratio	SC ₂	20	-	dB	

www.DataSheet4U.com







- (1) V_{VAGC} is VIF AGC voltage and can be measured at pin VAGC.
- (2) I_{TAGC} is tuner current in TV mode with R_{TOP} = 22 k Ω .
- (3) I_{TAGC} is tuner current in TV mode with R_{TOP} = 10 k Ω .
- (4) I_{TAGC} is tuner current in TV mode with $R_{TOP} = 0 \text{ k}\Omega$.

Fig 6. Typical VIF and tuner AGC characteristics.

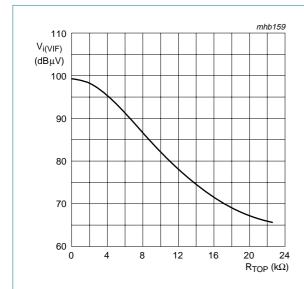


Fig 7. Typical tuner takeover point as a function of resistor R_{TOP} .

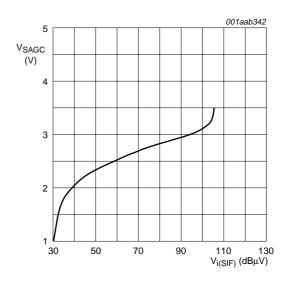
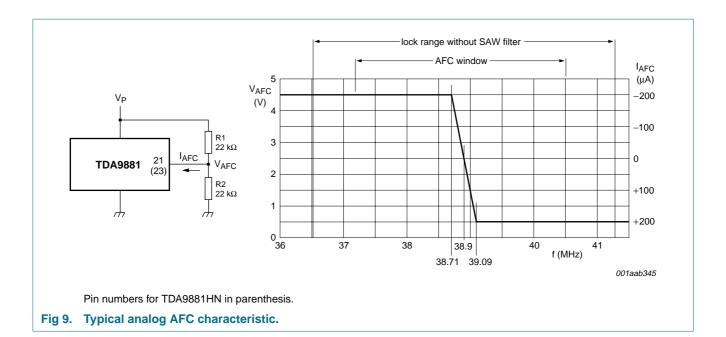


Fig 8. Typical SIF AGC characteristic.



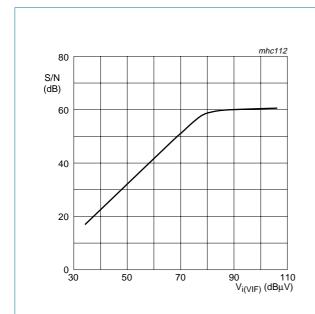
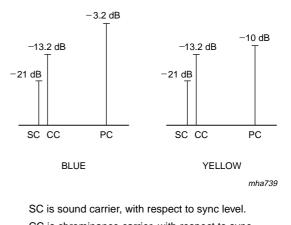


Fig 10. Typical signal-to-noise ratio as a function of VIF input voltage.

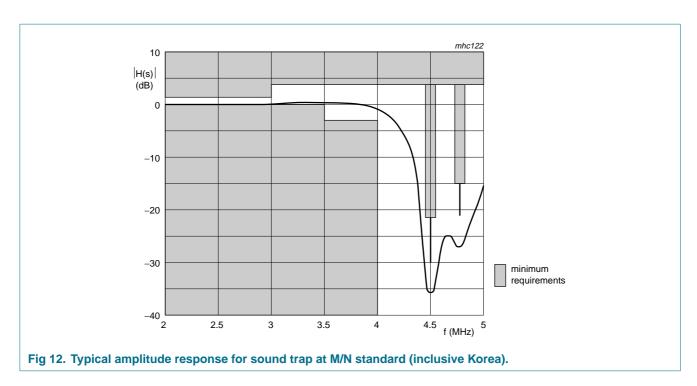


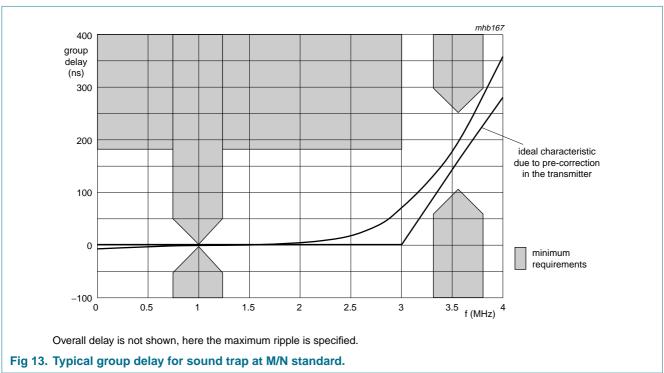
SC is sound carrier, with respect to sync level. CC is chrominance carrier, with respect to sync level.

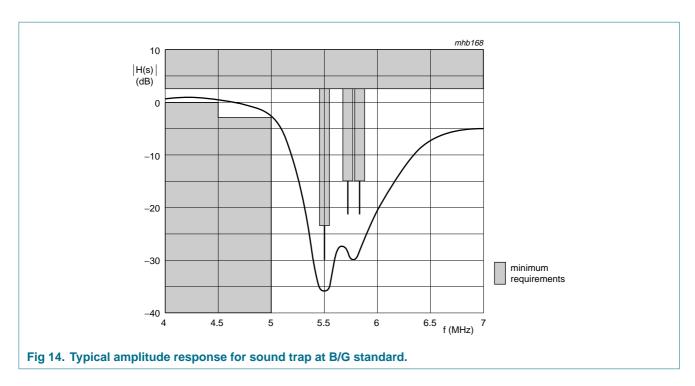
PC is picture carrier, with respect to sync level. The sound carrier levels are taking into account a sound shelf attenuation of 14 dB (SAW filter G1984M).

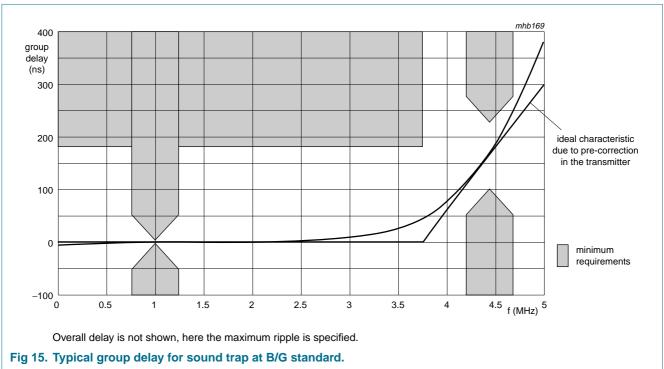
Fig 11. Input signal conditions.

Product data sheet

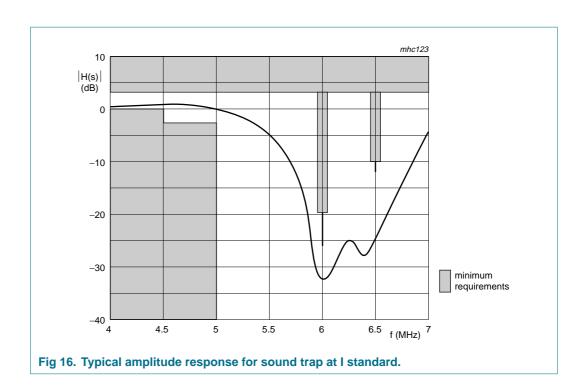


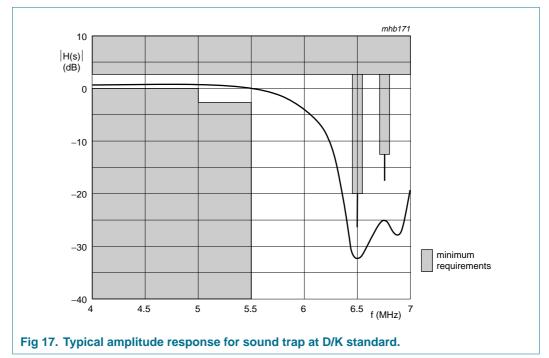


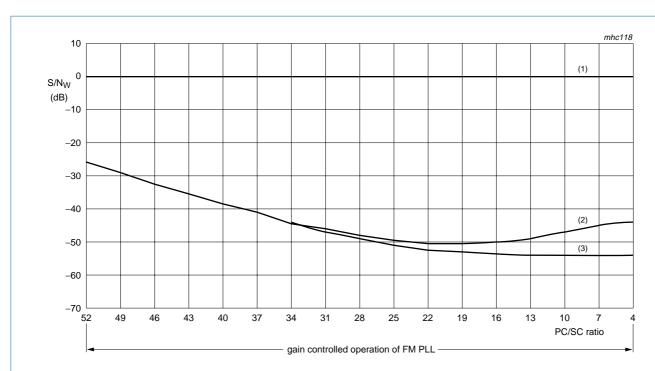




Product data sheet





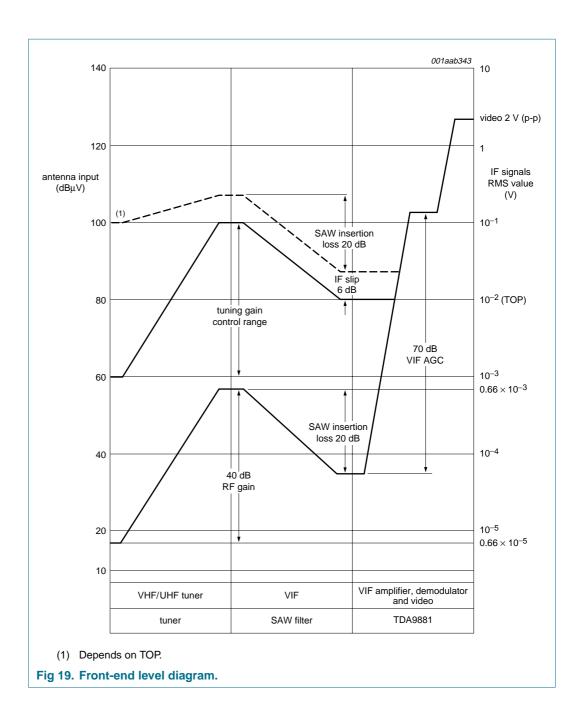


Conditions: PC/SC ratio is measured at pins VIF1 and VIF2; via transformer; 27 kHz FM deviation; 50 µs de-emphasis.

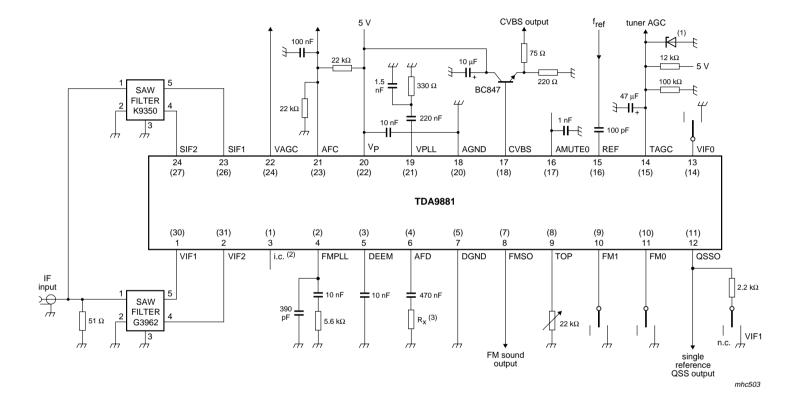
- Signal.
- (2) Noise at H-picture (CCIR weighted quasi peak).
- (3) Noise at black picture (CCIR weighted quasi peak).

Fig 18. Audio signal-to-noise ratio as a function of picture-to-sound carrier ratio in intercarrier mode.

31 of 42



12. **Application information**



Pin numbers for TDA9881HN in parenthesis.

- (1) Optional measures to improve ESD performance within a TV-set application.
- Internal connected; the pin must be left open-circuit.
- AF output signal reduction; see <u>Table note 19</u> of <u>Section 11</u>.

Fig 20. Application diagram of TDA9881.

www.DataSheet4U.com

Product data sheet

Rev. 01

16 November 2004

13.

Test information

www.DataSheet4U.com

AFC VIF PLL **CVBS** external tuner AGC output filter (1) reference V_{P} output output SIF 100 n.c. 1:1 input 22 100 150 Ω рF or 7 n.c. or V_P $22~\text{k}\Omega$ # 220 nF 1 nF SIF2 SIF1 VAGC AFC VPLL AGND AMUTE0 REF TAGC VIF0 **CVBS** 24 23 22 21 20 19 18 17 16 15 14 13 (27)(26)(24)(23)(21) (20)(18)(17)(16)(15)(14)(22)TDA9881 (31) (3) (1) (2) (4) (5) (8) (30)(7) (9) (10)(11)5 2 3 6 8 9 10 1 11 12 i.c. ⁽²⁾ QSSO VIF1 VIF2 **FMPLL** DEEM AFD DGND **FMSO** TOP FM1 FM0 VIF 1:1 input 2.2 kΩ # 470 nF 10 nF 📥 **╧** 10 nF 390 R_x (3) $22 \text{ k}\Omega$ $5.6~\text{k}\Omega$ VIF1 V_P n.c. \mathcal{H} V_P or or FM PLL FM sound single n.c. n.c. filter reference output QSS output mhc505

Pin numbers for TDA9881HN in parenthesis.

- (1) Different VIF loop filter in comparison with the application circuit due to different input characteristics (SAW filter or transformer).
- Internal connected; the pin must be left open-circuit.
- (3) AF output signal reduction; see Table note 19 of Section 11.

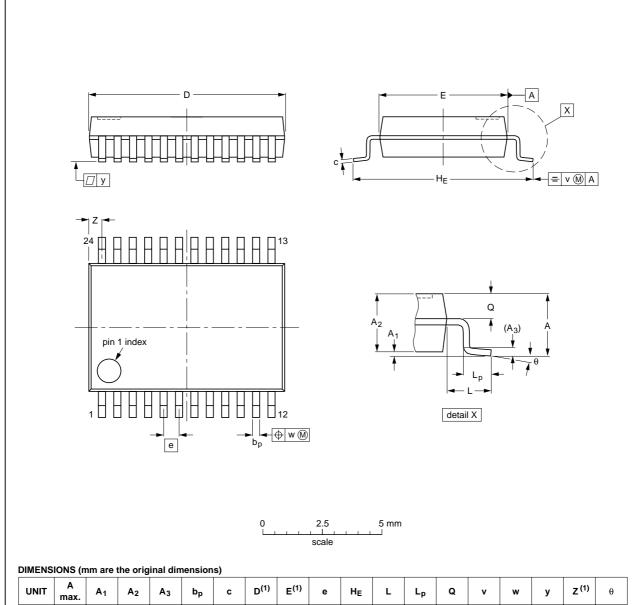
Fig 21. Test circuit.

TDA9881

14. Package outline

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



		(٠-,												
UN	IIT	A max.	A ₁	A ₂	A ₃	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Q	v	w	у	Z ⁽¹⁾	θ
m	m	2	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

Note

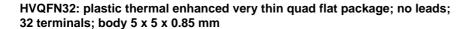
1. Plastic or metal protrusions of 0.2 mm maximum per side are not included.

OUTLINE		EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT340-1		MO-150			99-12-27 03-02-19

Fig 22. Package outline SOT340-1 (SSOP24).

9397 750 13417

Product data sheet



SOT617-3

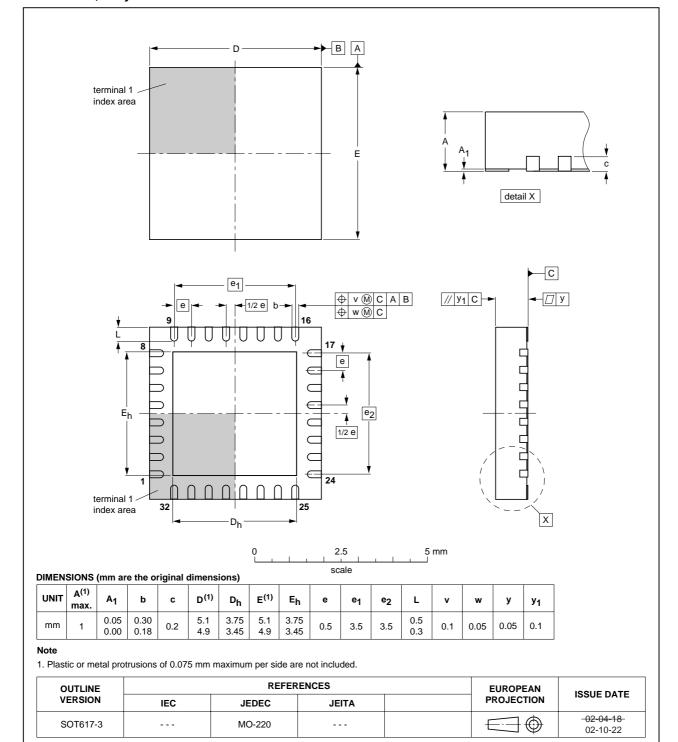


Fig 23. Package outline SOT617-3 (HVQFN32).

9397 750 13417



15. Soldering

15.1 Introduction to soldering surface mount packages

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *Data Handbook IC26; Integrated Circuit Packages* (document order number 9398 652 90011).

There is no soldering method that is ideal for all surface mount IC packages. Wave soldering can still be used for certain surface mount ICs, but it is not suitable for fine pitch SMDs. In these situations reflow soldering is recommended.

15.2 Reflow soldering

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement. Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing.

Several methods exist for reflowing; for example, convection or convection/infrared heating in a conveyor type oven. Throughput times (preheating, soldering and cooling) vary between 100 seconds and 200 seconds depending on heating method.

Typical reflow peak temperatures range from 215 °C to 270 °C depending on solder paste material. The top-surface temperature of the packages should preferably be kept:

- below 225 °C (SnPb process) or below 245 °C (Pb-free process)
 - for all BGA, HTSSON..T and SSOP..T packages
 - for packages with a thickness ≥ 2.5 mm
 - for packages with a thickness < 2.5 mm and a volume ≥ 350 mm³ so called thick/large packages.
- below 240 °C (SnPb process) or below 260 °C (Pb-free process) for packages with a thickness < 2.5 mm and a volume < 350 mm³ so called small/thin packages.

Moisture sensitivity precautions, as indicated on packing, must be respected at all times.

15.3 Wave soldering

Conventional single wave soldering is not recommended for surface mount devices (SMDs) or printed-circuit boards with a high component density, as solder bridging and non-wetting can present major problems.

To overcome these problems the double-wave soldering method was specifically developed.

If wave soldering is used the following conditions must be observed for optimal results:

- Use a double-wave soldering method comprising a turbulent wave with high upward pressure followed by a smooth laminar wave.
- For packages with leads on two sides and a pitch (e):
 - larger than or equal to 1.27 mm, the footprint longitudinal axis is preferred to be parallel to the transport direction of the printed-circuit board;

9397 750 13417

 smaller than 1.27 mm, the footprint longitudinal axis must be parallel to the transport direction of the printed-circuit board.

The footprint must incorporate solder thieves at the downstream end.

 For packages with leads on four sides, the footprint must be placed at a 45° angle to the transport direction of the printed-circuit board. The footprint must incorporate solder thieves downstream and at the side corners.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Typical dwell time of the leads in the wave ranges from 3 seconds to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

15.4 Manual soldering

Fix the component by first soldering two diagonally-opposite end leads. Use a low voltage (24 V or less) soldering iron applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C.

When using a dedicated tool, all other leads can be soldered in one operation within 2 seconds to 5 seconds between 270 °C and 320 °C.

15.5 Package related soldering information

Table 13: Suitability of surface mount IC packages for wave and reflow soldering methods

Package [1]	Soldering method		
	Wave	Reflow [2]	
BGA, HTSSONT 3, LBGA, LFBGA, SQFP, SSOPT 3, TFBGA, VFBGA, XSON	not suitable	suitable	
DHVQFN, HBCC, HBGA, HLQFP, HSO, HSOP, HSQFP, HSSON, HTQFP, HTSSOP, HVQFN, HVSON, SMS	not suitable 4	suitable	
PLCC [5], SO, SOJ	suitable	suitable	
LQFP, QFP, TQFP	not recommended [5] [6]	suitable	
SSOP, TSSOP, VSO, VSSOP	not recommended [7]	suitable	
CWQCCNL[8], PMFP[9], WQCCNL[8]	not suitable	not suitable	

For more detailed information on the BGA packages refer to the (LF)BGA Application Note (AN01026);
 order a copy from your Philips Semiconductors sales office.

- [2] All surface mount (SMD) packages are moisture sensitive. Depending upon the moisture content, the maximum temperature (with respect to time) and body size of the package, there is a risk that internal or external package cracks may occur due to vaporization of the moisture in them (the so called popcorn effect). For details, refer to the Drypack information in the Data Handbook IC26; Integrated Circuit Packages; Section: Packing Methods.
- [3] These transparent plastic packages are extremely sensitive to reflow soldering conditions and must on no account be processed through more than one soldering cycle or subjected to infrared reflow soldering with peak temperature exceeding 217 °C ± 10 °C measured in the atmosphere of the reflow oven. The package body peak temperature must be kept as low as possible.

9397 750 13417

© Koninklijke Philips Electronics N.V. 2004. All rights reserved.

www.DataSheet4U.com



- [4] These packages are not suitable for wave soldering. On versions with the heatsink on the bottom side, the solder cannot penetrate between the printed-circuit board and the heatsink. On versions with the heatsink on the top side, the solder might be deposited on the heatsink surface.
- [5] If wave soldering is considered, then the package must be placed at a 45° angle to the solder wave direction. The package footprint must incorporate solder thieves downstream and at the side corners.
- [6] Wave soldering is suitable for LQFP, QFP and TQFP packages with a pitch (e) larger than 0.8 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.65 mm.
- [7] Wave soldering is suitable for SSOP, TSSOP, VSO and VSSOP packages with a pitch (e) equal to or larger than 0.65 mm; it is definitely not suitable for packages with a pitch (e) equal to or smaller than 0.5 mm.
- [8] Image sensor packages in principle should not be soldered. They are mounted in sockets or delivered pre-mounted on flex foil. However, the image sensor package can be mounted by the client on a flex foil by using a hot bar soldering process. The appropriate soldering profile can be provided on request.
- [9] Hot bar soldering or manual soldering is suitable for PMFP packages.



16. Revision history

Table 14: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
TDA9881_1	20041116	Product data sheet	-	9397 750 13417	-

17. Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

- [1] Please consult the most recently issued data sheet before initiating or completing a design.
- [2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- [3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

18. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

19. Disclaimers

Life support — These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes in the products - including circuits, standard cells, and/or software - described or contained herein in order to improve design and/or performance. When the product is in full production (status 'Production'), relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN). Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

20. Contact information

For additional information, please visit: http://www.semiconductors.philips.com
For sales office addresses, send an email to: sales.addresses@www.semiconductors.philips.com

21. Contents

1	General description	. 1
2	Features	. 1
3	Applications	. 1
4	Quick reference data	. 2
5	Ordering information	. 3
6	Block diagram	
7	Pinning information	
7.1	Pinning	
7.2	Pin description	
8	Functional description	. 7
8.1	VIF amplifier	. 7
8.2	Tuner AGC and VIF AGC	. 7
8.3	VIF AGC detector	
8.4	FPLL detector	
8.5	VCO and divider	
8.6	AFC and digital acquisition help circuit	
8.7 8.8	Video demodulator and amplifier	
o.o 8.9	SIF amplifier	
8.10	SIF AGC detector	
8.11	Single reference QSS mixer	
8.12	FM demodulator and acquisition help circuit .	
8.13	Audio amplifier and mute time constant	11
8.14	Internal voltage stabilizer	
8.15	Logic	
9	Limiting values	
10	Thermal characteristics	13
11	Characteristics	13
12	Application information	33
13	Test information	34
14	Package outline	35
15	Soldering	
15.1	Introduction to soldering surface mount	
	packages	37
15.2	Reflow soldering	37
15.3	Wave soldering	
15.4	Manual soldering	
15.5	Package related soldering information	
16	Revision history	
17	Data sheet status	
18	Definitions	41
19	Disclaimers	41
20	Contact information	41



© Koninklijke Philips Electronics N.V. 2004

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Date of release: 16 November 2004 Document number: 9397 750 13417

Published in The Netherlands